ABSTRACT

METHOD FOR PROCESSING WAFER

To enable handling a wafer facilitate during processing even when the wafer is formed thin, a protective member is stuck through an adhesive agent to an outer-peripheral surplus region of a front surface of the wafer, the region being formed with no individual devices, and a back surface of the wafer is ground in a state where the whole front surface of the wafer is supported by the protective member. Since an outer periphery of the wafer is reinforced by the protective member, the wafer can be easily handled even after having been thinned by the grinding.

Figure 2.